

## **Identification of Assembly Solutions for Low Cost Packaging of MEMS Components by Assembly of Bare Microsystem Dies Directly on Substrates**

### **Objectives**

- To identify MEMS devices suitable for chip-on-board assembly
- To review the current approaches used in MEMS assembly
- To identify suitable substrates for CoB MEMS assembly
- To identify the best MEMS – substrate/process combinations for CoB assembly

### **Partners involved**

- Heriot Watt University
- QinetiQ
- Fraunhofer IMS
- BUTE

### **Summary of results**

To be added

### **Offer to industry**

- Advice on CoB MEMS packaging technology
- Advice on MEMS packaging materials and processes

### **Contact**

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### **Project status**

Just started